

QuickLogic First to Offer eFPGA Technology on SMIC 40nm Low Leakage Process

SUNNYVALE, Calif. and SHANGHAI, Sept. 12, 2017 /PRNewswire/ -- Semiconductor Manufacturing International Corporation ("SMIC"; NYSE: SMI; SEHK: 0981.HK), one of the leading semiconductor foundries in the world and the largest and most advanced foundry in mainland China, and QuickLogic Corporation (NASDAQ: QUIK), a developer of ultra-low power multi-core voice-enabled SoCs, embedded FPGA IP, display bridge and programmable logic solutions, today announced the availability of QuickLogic's [ArcticPro™ embedded FPGA \(eFPGA\)](#) technology on SMIC's 40nm Low Leakage (40LL) process. QuickLogic's advanced architecture, mature software and IP ecosystem, in combination with the SMIC 40LL process, offers SoC designers an easy-to-implement, highly reliable and extremely low power eFPGA solution. The ArcticPro eFPGA technology, which is already in production on a variety of leading processes, is the industry's first eFPGA IP to be offered on the SMIC 40LL technology node.

QuickLogic's ArcticPro eFPGA, in the SMIC 40LL process, gives developers of SoCs the ability to add a high degree of post manufacturing design flexibility to devices. Because it's a single device platform, multiple chip variants can be created from a single mask set, enabling customization to address fragmented and/or rapidly evolving standards. This not only equates to a significant reduction in cost, but also provides developers with the flexibility they need to support new and unique customer requirements and to target new markets. The ultra-low power consumption of the ArcticPro eFPGA makes it especially well-suited for handheld, wearable and IoT endpoint applications, all of which require a long battery life.

Dr. Tianshen Tang, EVP of Design Service, at SMIC, stated "This is the first eFPGA IP offering to be available on the SMIC 40LL process. We chose QuickLogic because the company has decades of experience with low-power FPGA architectures and supporting software. Now our customers can benefit from this technology and its unprecedented post-manufacturing flexibility."

Brian Faith, QuickLogic's president and CEO, added, "Supporting the SMIC 40LL process is a significant step forward for ArcticPro eFPGA technology. It's now broadly available on a popular low-power process, well-supported and easy to implement. We expect these factors to drive broad adoption for a wide range of low power SoC designs."

Availability:

QuickLogic's ArcticPro eFPGA IP on the SMIC 40LL process and an evaluation board are available today. For additional information, please visit www.quicklogic.com/technologies/efpga-ip/arcticpro-efpga or email efpga@quicklogic.com.

About SMIC

Semiconductor Manufacturing International Corporation ("SMIC"; NYSE: SMI; SEHK: 981) is one of the leading semiconductor foundries in the world and the largest and most advanced foundry in mainland China. SMIC provides integrated circuit (IC) foundry and technology services on process nodes from 0.35 micron to 28 nanometer. Headquartered in Shanghai, China, SMIC has an international manufacturing and service base. In China, SMIC has a 300mm wafer fabrication facility (fab) and a 200mm mega-fab in Shanghai; a 300mm mega-fab and a majority-owned 300mm fab for advanced nodes in Beijing; 200mm fabs in Tianjin and Shenzhen; and a majority-owned joint-venture 300mm bumping facility in Jiangyin; additionally, in Italy SMIC has a majority-owned 200mm fab. SMIC also has marketing and customer service offices in the U.S., Europe, Japan, and Taiwan, and a representative office in Hong Kong. For more information, please visit www.smics.com.

Safe Harbor Statements

(Under the Private Securities Litigation Reform Act of 1995)

This press release contains, in addition to historical information, "forward-looking statements" within the meaning of the "safe harbor" provisions of the U.S. Private Securities Litigation Reform Act of 1995. These forward-looking statements are based on SMIC's current assumptions, expectations and projections about future events. SMIC uses words like "believe," "anticipate," "intend," "estimate," "expect," "project," "target" and similar expressions to identify forward looking statements, although not all forward-looking statements contain these words. These forward-looking statements are necessarily estimates reflecting the best judgment of SMIC's senior management and involve significant risks, both known and unknown, uncertainties and other factors that may cause SMIC's actual performance, financial condition or results of operations to be materially different from those suggested by the forward-looking statements including, among others, risks associated with cyclicalities and market conditions in the semiconductor industry, intense competition in the semiconductor industry, SMIC's reliance on a small number of customers, timely wafer acceptance by SMIC's customers, timely introduction of new technologies, SMIC's ability to ramp new products into volume, supply and demand for semiconductor foundry services, industry overcapacity, shortages in equipment, components and raw materials, availability of manufacturing capacity, financial stability in end markets, orders or judgments from pending litigation, intensive intellectual property litigation in semiconductor industry, general economic conditions and fluctuations in currency exchange rates.

In addition to the information contained in this press release, you should also consider the information contained in our other filings with the SEC, including our annual report on Form 20-F filed with the SEC on April 27, 2017, especially in the "Risk Factors" section and such other documents that we may file with the SEC or The Hong Kong Stock Exchange Limited ("SEHK") from time to time, including current reports on Form 6-K. Other unknown or unpredictable factors also could have material adverse effects on our future results, performance or achievements. In light of these risks, uncertainties, assumptions and factors, the forward-looking events discussed in this press release may not occur. You are cautioned not to place undue reliance on these forward-looking statements, which speak only as of the date stated or, if no date is stated, as of the date of this press release. Except as may be required by law, SMIC undertakes no obligation and does not intend to update any forward-looking statement, whether as a result of new information, future events or otherwise.

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About QuickLogic

QuickLogic Corporation (NASDAQ: QUIK) enables OEMs to maximize battery life for highly differentiated, immersive user experiences with Smartphone, Wearable and IoT devices. QuickLogic delivers these benefits through industry leading ultra-low power customer programmable SoC semiconductor solutions, embedded software, and algorithms for always-on voice and sensor processing. The company's embedded FPGA initiative also enables SoC designers to easily implement post production changes, and increase revenue by providing hardware programmability to their end customers. For more information about QuickLogic, visit www.quicklogic.com.

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